

Cree CGH40010 GaN HEMT Teardown and Technology Analysis

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1. Product Identification

Manufacturer	Device ID	Date/lot code
Cree	CGH40010FE, Package 440166	2390/22808

2. External Appearance and Principal Dimensions

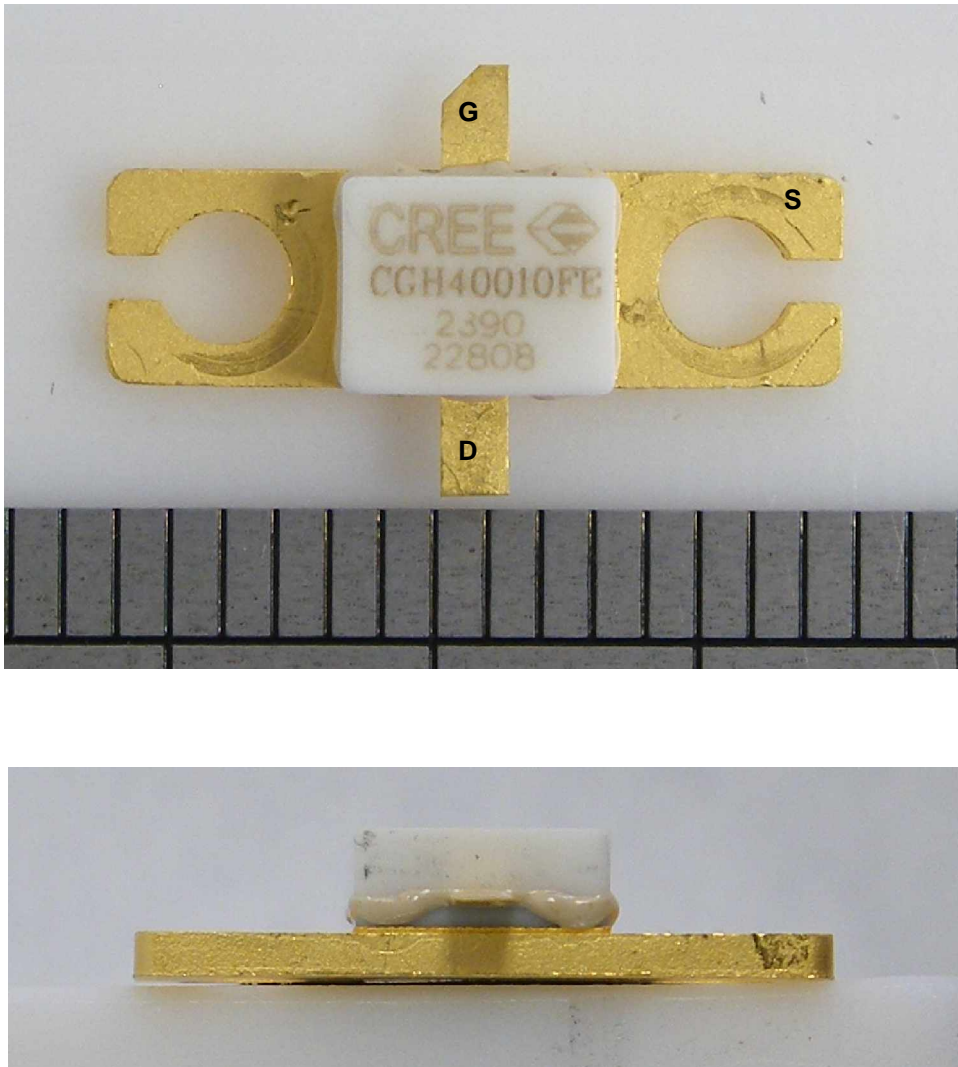


Figure 2.1: Devices as received, top and side view. The markings of the ruler are 1mm apart.

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